



**Thermal CFP2000-US** 碳纤维高导热垫片采用碳纤维定向排列技术进行制备，其具有超高的导热系数 20.0W/m.K，同时具备良好的力学性能。该产品具有较强的弥合公差能力，可有效提升芯片散热效率。

**Thermal CFP2000-US** carbon fiber based high thermal conductive gap pad is designed based on carbon fiber orientation technology with thermal conductivity of 20.0W/m.K. The product provides good mechanical properties, as well as excellent gap filling ability to improve chip dissipation efficiency.

### Features 特性

- Thermal Conductivity 导热系数 20.0 W/m·K
- Low Compress Stress 低压缩应力
- High Rebound Performance 高回弹
- High Reliability 高可靠性

### Applications 产品应用

- Consumer Electronics 消费电子
- Network Equipment 网通设备
- Data Center 数据中心
- Optical Module 光模块
- Projector 投影仪

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
<b>Composition</b> 主要成分	Silicone Filled with Carbon Filler and Thermal Powder 硅胶&碳纤维&导热粉体	—	—
<b>Color</b> 颜色	Dark Gray 深灰色	—	Visual 目视
<b>Thermal Conductivity</b> 导热系数	20.0	W/m·K	ASTM D5470
<b>Thickness</b> 厚度	0.3 - 5.0	mm	ASTM D374
<b>Hardness</b> 硬度 (Shore 00)	35	—	ASTM D2240
<b>Density</b> 密度	1.9	g/cm <sup>3</sup>	ASTM D792
<b>Temperature Range</b> 耐温范围	-40 - 200	°C	—
<b>Breakdown Voltage</b> 击穿强度	< 100	V/mm	ASTM D149
<b>Volume Resistivity</b> 体积电阻率	< 500	Ω.cm	ASTM D257
<b>Flame Rating</b> 阻燃等级	V-0	—	UL 94
<b>RoHS Compliance</b> 合规性	YES	—	—
<b>Shelf Life</b> 保存期	24	month	25±5°C ≤50% RH

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

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